

**WEST**

Help

Logout

Interrupt

09/855,609

Main Menu

Search Form

Posting Counts

Show S Numbers

Edit S Numbers

Preferences

Cases

**Search Results -**

Terms	Documents
L1 and (TMAT or TDEAT)	0

Database:

US Patents Full-Text Database

US Pre-Grant Publication Full-Text Database

JPO Abstracts Database

EPO Abstracts Database

Derwent World Patents Index

IBM Technical Disclosure Bulletins

Search:

L9

Refine Search

Recall Text

Clear

**Search History**DATE: Sunday, March 09, 2003 [Printable Copy](#) [Create Case](#)**Set Name Query**

side by side

**Hit Count Set Name**

result set

DB=USPT; PLUR=YES; OP=ADJ

<u>L9</u>	L1 and (TMAT or TDEAT)	0	<u>L9</u>
<u>L8</u>	L7 and (TMAT or TDEAT)	1	<u>L8</u>
<u>L7</u>	stack? near2 (barrier)	51	<u>L7</u>
<u>L6</u>	L4 and copper	9	<u>L6</u>
<u>L5</u>	L4 and serially	0	<u>L5</u>
<u>L4</u>	stacked near2 (barrier adj layer) and adhesion	13	<u>L4</u>
<u>L3</u>	L1 and(TDMAT or TDEAT or TiCl4)	0	<u>L3</u>
<u>L2</u>	L1 and (adhesion adj layer) and (TDMAT or TDEAT or TiCl4)	0	<u>L2</u>
<u>L1</u>	stacked near2 (barrier adj layer)	100	<u>L1</u>

END OF SEARCH HISTORY

**WEST**[Generate Collection](#)[Print](#)**Search Results - Record(s) 1 through 1 of 1 returned.**☐ 1. Document ID: US 5942799 A

L8: Entry 1 of 1

File: USPT

Aug 24, 1999

US-PAT-NO: 5942799

DOCUMENT-IDENTIFIER: US 5942799 A

TITLE: Multilayer diffusion barriers

Full	Title	CIT.1	REV.1	CLS.1	REF.1	SEQ.1	ATT.1
NAW.1							

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Terms	Documents
L7 and (TMAT or TDEAT)	1

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**WEST**[Generate Collection](#)[Print](#)**Search Results - Record(s) 1 through 9 of 9 returned.**☐ 1. Document ID: US 6407422 B1

L6: Entry 1 of 9

File: USPT

Jun 18, 2002

US-PAT-NO: 6407422

DOCUMENT-IDENTIFIER: US 6407422 B1

TITLE: Oxygen diffusion blocking semiconductor capacitor

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	RWMC
Draw Desc	Image										

☐ 2. Document ID: US 6379977 B1

L6: Entry 2 of 9

File: USPT

Apr 30, 2002

US-PAT-NO: 6379977

DOCUMENT-IDENTIFIER: US 6379977 B1

TITLE: Method of manufacturing ferroelectric memory device

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	RWMC
Draw Desc	Image										

☐ 3. Document ID: US 6245667 B1

L6: Entry 3 of 9

File: USPT

Jun 12, 2001

US-PAT-NO: 6245667

DOCUMENT-IDENTIFIER: US 6245667 B1

TITLE: Method of forming via

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	RWMC
Draw Desc	Image										

☐ 4. Document ID: US 6242808 B1

L6: Entry 4 of 9

File: USPT

Jun 5, 2001

US-PAT-NO: 6242808  
DOCUMENT-IDENTIFIER: US 6242808 B1

TITLE: Semiconductor device with copper wiring and semiconductor device manufacturing method

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	RWMC
Draw Desc	Image										

☐ 5. Document ID: US 6207268 B1

L6: Entry 5 of 9                      File: USPT                      Mar 27, 2001

US-PAT-NO: 6207268  
DOCUMENT-IDENTIFIER: US 6207268 B1

TITLE: Transfer sheet, and pattern-forming method

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	RWMC
Draw Desc	Image									

☐ 6. Document ID: US 6140231 A

L6: Entry 6 of 9                      File: USPT                      Oct 31, 2000

US-PAT-NO: 6140231  
DOCUMENT-IDENTIFIER: US 6140231 A

TITLE: Robust diffusion barrier for Cu metallization ✓

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	RWMC
Draw Desc	Image									

☐ 7. Document ID: US 6016011 A

L6: Entry 7 of 9                      File: USPT                      Jan 18, 2000

US-PAT-NO: 6016011  
DOCUMENT-IDENTIFIER: US 6016011 A

TITLE: Method and apparatus for a dual-inlaid damascene contact to sensor

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	RWMC
Draw Desc	Image									

☐ 8. Document ID: US 5506449 A

L6: Entry 8 of 9

File: USPT

Apr 9, 1996

US-PAT-NO: 5506449

DOCUMENT-IDENTIFIER: US 5506449 A

TITLE: Interconnection structure for semiconductor integrated  
circuit and manufacture of the same

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

RMC

☐ 9. Document ID: US 5335138 A

L6: Entry 9 of 9

File: USPT

Aug 2, 1994

US-PAT-NO: 5335138

DOCUMENT-IDENTIFIER: US 5335138 A

TITLE: High dielectric constant capacitor and method of manufacture

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

RMC

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Terms	Documents
L4 and copper	9

Display Format:

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Change Format

[Previous Page](#)[Next Page](#)

**WEST**[Generate Collection](#)[Print](#)**Search Results - Record(s) 1 through 10 of 13 returned.**☒ 1. Document ID: US 6407422 B1

L4: Entry 1 of 13

File: USPT

Jun 18, 2002

US-PAT-NO: 6407422

DOCUMENT-IDENTIFIER: US 6407422 B1

TITLE: Oxygen diffusion blocking semiconductor capacitor

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

[KVMC](#)☐ 2. Document ID: US 6406802 B1

L4: Entry 2 of 13

File: USPT

Jun 18, 2002

US-PAT-NO: 6406802

DOCUMENT-IDENTIFIER: US 6406802 B1

TITLE: Organic electroluminescent color display

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

[KVMC](#)☐ 3. Document ID: US 6379977 B1

L4: Entry 3 of 13

File: USPT

Apr 30, 2002

US PAT NO: 6379977

DOCUMENT-IDENTIFIER: US 6379977 B1

TITLE: Method of manufacturing ferroelectric memory device

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

[KVMC](#)☐ 4. Document ID: US 6245667 B1

L4: Entry 4 of 13

File: USPT

Jun 12, 2001

US-PAT-NO: 6245667

DOCUMENT-IDENTIFIER: US 6245667 B1

TITLE: Method of forming via

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

KIMC

☐ 5. Document ID: US 6242808 B1

L4: Entry 5 of 13

File: USPT

Jun 5, 2001

US-PAT-NO: 6242808

DOCUMENT-IDENTIFIER: US 6242808 B1

TITLE: Semiconductor device with copper wiring and semiconductor device manufacturing method

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

KIMC

☐ 6. Document ID: US 6228701 B1

L4: Entry 6 of 13

File: USPT

May 8, 2001

US-PAT-NO: 6228701

DOCUMENT-IDENTIFIER: US 6228701 B1

TITLE: Apparatus and method for minimizing diffusion in stacked capacitors formed on silicon plugs

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

KIMC

☐ 7. Document ID: US 6207268 B1

L4: Entry 7 of 13

File: USPT

Mar 27, 2001

US-PAT-NO: 6207268

DOCUMENT-IDENTIFIER: US 6207268 B1

TITLE: Transfer sheet, and pattern-forming method

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

KIMC

☐ 8. Document ID: US 6140231 A



L4: Entry 8 of 13

File: USPT

Oct 31, 2000

US-PAT-NO: 6140231

DOCUMENT-IDENTIFIER: US 6140231 A

TITLE: Robust diffusion barrier for Cu metallization

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

RMMC

☐ 9. Document ID: US 6016011 A

L4: Entry 9 of 13

File: USPT

Jan 18, 2000

US-PAT-NO: 6016011

DOCUMENT-IDENTIFIER: US 6016011 A

TITLE: Method and apparatus for a dual-inlaid damascene contact to sensor

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

RMMC

☐ 10. Document ID: US 5506449 A

L4: Entry 10 of 13

File: USPT

Apr 9, 1996

US-PAT-NO: 5506449

DOCUMENT-IDENTIFIER: US 5506449 A

TITLE: Interconnection structure for semiconductor integrated circuit and manufacture of the same

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

RMMC

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Terms	Documents
stacked near2 (barrier adj layer) and adhesion	13

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